GH17805B2AS/GH17805B2BS

■ Features

- \$\phi\$5.6mm open type insert lead frame structure
 (Optically compatible with the conventional \$\phi\$5.6mm package)
- (2) Maximum optical power output: 5mW
- (3) Wavelength: TYP. 780nm
- (4) Low current drive type

Model No.

- (1) GH17805B2AS Dual power supply
- (2) GH17805B2BSSingle power supply

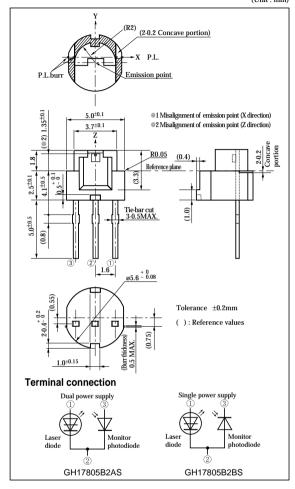
Applications

- (1) Audio CD players
- (2) CD-ROM drives

Insert Frame Structure, Resin Type Laser Diode for Audio CD/CD-ROM Drive(780nm-5mW)

Outline Dimensions

(Unit:mm)



■ Absolute Maximum Ratings

(Tc=25°C *1)

Param	Symbol	Rating	Unit					
Optical power outp	ut	Po	mW					
Reverse voltage	Laser	V_{rl}	2	V				
	Monitor photodiode	$V_{\rm rd}$	30					
*1 Operating tempera	ture	Top(c)	-10 to +70	°C				
Storage temperatur	Tstg	-40 to +85	°C					
*2 Soldering temperat	Tsld	260	°C					

^{*1} Case temperature

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^{*2} At the position of 1.6mm or more from the lead base (5s)

■ Electro-optical Characteristics*1

(Tc=25°C)

Paramete	er	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Threshold current		Ith	_	-	(35)	45	mA
Operating current		Iop		-	(42)	52	mA
Operating voltage		V_{op}	Po=3mW	-	(1.9)	2.3	V
Wavelength		λ_{p}		770	(780)	795	nm
Half intensity and b	*2*3 Parallel	θ//		8	(11)	15	۰
	*2*3 Perpendicular	$\theta \perp$		29	(37)	49	۰
*4 Ripple		Rı		-	-	±20	%
3.61.11.	*3 Parallel	$\Delta \theta //$		-	-	±1.5	۰
Misalignment angle	*3 Perpendicular	$\Delta \theta \perp$		-	-	±3	•
Differential efficiency		ηd	$\frac{2mW}{I(3mW)\cdot I(1mW)}$	0.15	(0.35)	0.6	mW/mA
Interference pattern i	ntensity	α	Po=3mW	-	-	0.97	-
Kink		K-LI	_	-	-	10	%

^{*1} Initial value, CW (Continuous Wave) drive

■ Electrical Characteristics of Photodiode (GH17805B2AS)

(Tc=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current	Im	Po=3mW, Vrd=5V	0.1	(0.28)	0.45	mA
Dark current	ΙD	V _{rd} =5V	-	-	150	nA

(GH17805B2BS) (Tc=25°C)

						()
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current	Im	_	0.05	(0.15)	0.4	mA
Dark current	ΙD	$V_{\rm rd}=5V$	-	-	150	nA

Operating and handling precautions

- This product employs open type package. Be careful not to touch directly to a gold wire, a laser chip, and a monitor sub-mount chip, or characteristics may be damaged.
- (2) The lead pins of this product consist of silver-plating.
 - Do not operate under the conditions of freezing or due formation. The use in such condition may cause short circuit due to silver migration.
- (3) Please finish soldering within 7 days, or keep the products in the N2-purged box after opening the package to prevent them from silver oxidization or damage to solderability.

^{*2} Angle at 50% peak intensity (full-width at half-maximum)

^{*3} Parallel to junction plane (X-Z plane), Perpendicular to the junction plane (Y-Z plane)

 $^{^{\}oplus 4}$ R= $\Delta P/P$ ΔP : the maximum deviation of the far field pattern from its approximate curve P: the peak of the approximate curve

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